- **3-State Buffer-Type Outputs Drive Bus Lines Directly**
- **Bus-Structured Pinout**
- **Choice of True or Inverting Logic**
  - **SN54ALS874B, SN74ALS874B, SN74AS874 Have True Outputs**
  - **SN74ALS876A, SN74AS876 Have Inverting Outputs**
- **Asynchronous Clear**
- **Package Options Include Plastic Small-Outline (DW) Packages, Plastic (FN) and Ceramic (FK) Chip Carriers, and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs**

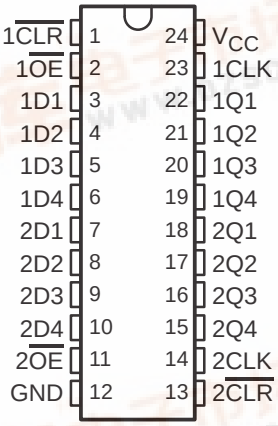
description

These dual 4-bit D-type edge-triggered flip-flops feature 3-state outputs designed specifically as bus drivers. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

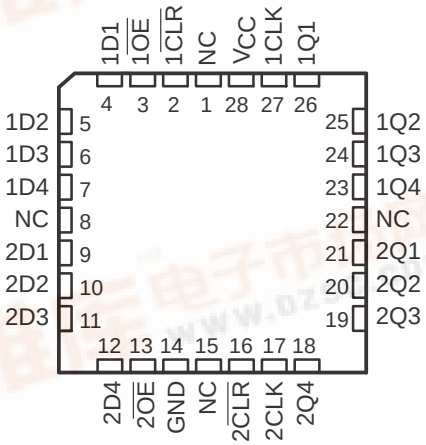
The edge-triggered flip-flops enter data on the low-to-high transition of the clock (CLK) input. The SN54ALS874B, SN74ALS874B, and SN74AS874 have clear ($\overline{CLR}$) inputs and noninverting Q outputs. The SN74ALS876A and SN74AS876 have preset ($\overline{PRE}$) inputs and inverting $\overline{Q}$ outputs; taking $\overline{PRE}$ low causes the four Q or $\overline{Q}$ outputs to go low independently of the clock.

The SN54ALS874B is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS874B, SN74ALS876A, SN74AS874, and SN74AS876 devices are characterized for operation from 0°C to 70°C.

SN54ALS874B . . . JT PACKAGE
SN74ALS874B, SN74AS874 . . . DW OR NT PACKAGE
(TOP VIEW)

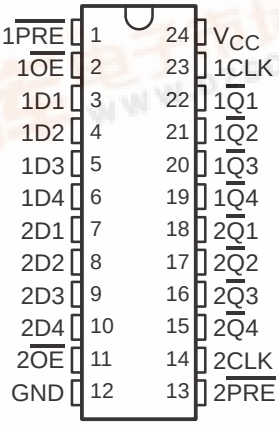


SN54ALS874B . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

SN74ALS876A, SN74AS876 . . . DW OR NT PACKAGE
(TOP VIEW)



Function Tables

SN54ALS874B, SN74ALS874B, SN74AS874 (each flip-flop)

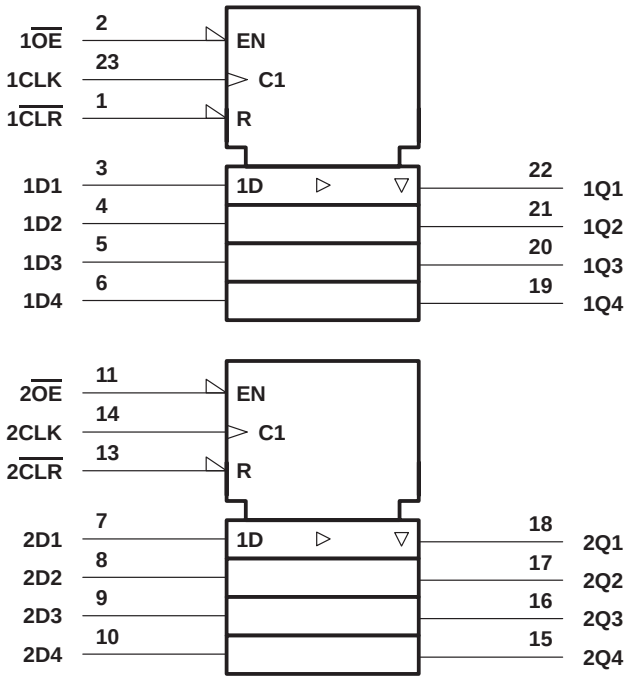
INPUTS				OUTPUT
$\overline{OE}$	$\overline{CLR}$	CLK	D	Q
L	L	X	X	L
L	H	↑	H	H
L	H	↑	L	L
L	H	L	X	Q_0
H	X	X	X	Z

SN74ALS876A, SN74AS876 (each flip-flop)

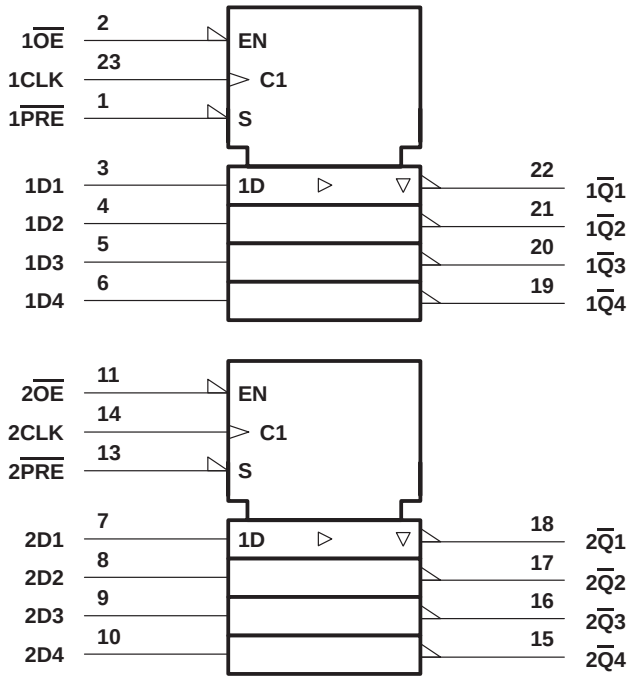
INPUTS				OUTPUT
$\overline{OE}$	$\overline{PRE}$	CLK	D	$\overline{Q}$
L	L	X	X	L
L	H	↑	H	L
L	H	↑	L	H
L	H	L	X	$\overline{Q}_0$
H	X	X	X	Z

logic symbols†

SN54ALS874B, SN74ALS874B, SN74AS874



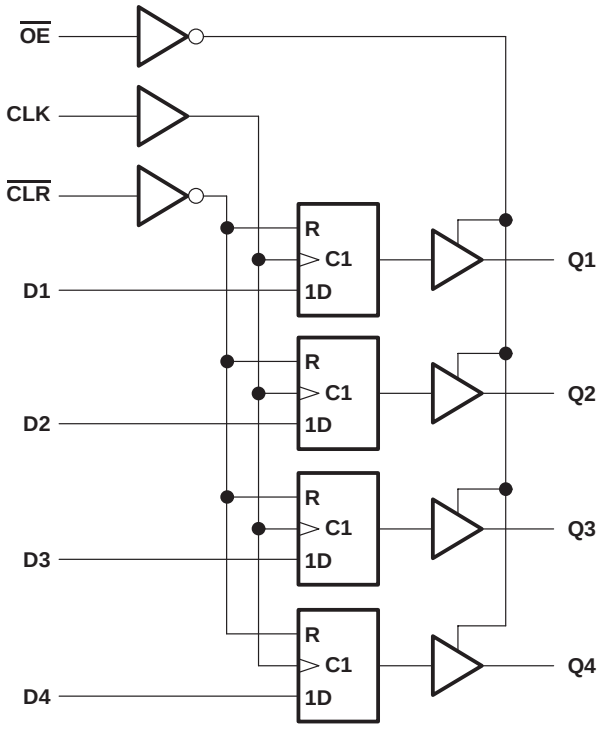
SN74ALS876A, SN74AS876



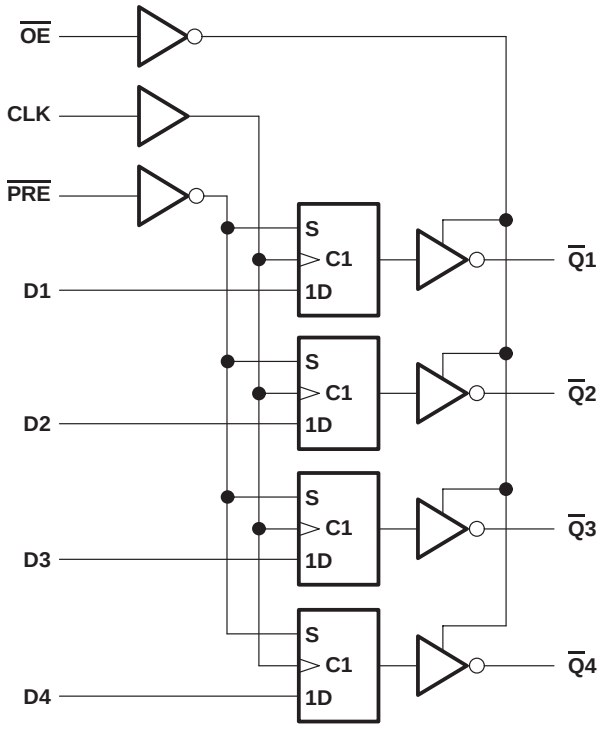
† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagrams (positive logic)

SN54ALS874B, SN74ALS874B, SN74AS874
(each quad flip-flop)



SN74ALS876A, SN74AS876
(each quad flip-flop)



Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I . . . . . 7 V
Voltage applied to a disabled 3-state output . . . . . 5.5 V
Operating free-air temperature range, T_A: SN54ALS874B . . . . . –55°C to 125°C
SN74ALS874B, SN74ALS876A . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54ALS874B			SN74ALS874B SN74ALS876A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current				–1			–2.6	mA
I_{OL}	Low-level output current				12			24	mA
f_{clock}	Clock frequency		0		25	0		30	MHz
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	15			10			ns
		CLK high	20			16.5			
		CLK low	20			16.5			
t_{su}	Setup time before CLK↑	Data	15			15			ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	15			10			
t_h	Hold time, data after CLK↑		4			0			ns
T_A	Operating free-air temperature		–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS874B			SN74ALS874B SN74ALS876A			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = –0.4 mA	V_{CC} –2			V_{CC} –2			V
		V_{CC} = 4.5 V	I_{OH} = –1 mA	2.4	3.3					
			I_{OH} = –2.6 mA				2.4	3.2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 24 mA					0.35	0.5	
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			20			20	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.4 V			–20			–20	µA
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}		V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}		V_{CC} = 5.5 V,	V_I = 0.4 V			–0.2			–0.2	mA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.25 V	–20		–112	–30		–112	mA
I_{CC}	′ALS874B	V_{CC} = 5.5 V	Outputs high		14	21		14	21	mA
			Outputs low		19	30		19	30	
			Outputs disabled		20	32		20	32	
	SN74ALS876A	V_{CC} = 5.5 V	Outputs high					14	21	
			Outputs low					18	29	
			Outputs disabled					20	31	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†				UNIT
			SN54ALS874B		SN74ALS874B		
			MIN	MAX	MIN	MAX	
f_{max}			25		30		MHz
t_{PLH}	CLK	Any Q	4	18	4	14	ns
t_{PHL}			4	16	4	14	
t_{PHL}	$\overline{CLR}$	Any Q	5	23	5	17	ns
t_{PZH}	$\overline{OE}$	Any Q	4	24	4	18	ns
t_{PZL}			4	21	4	18	
t_{PHZ}	$\overline{OE}$	Any Q	2	15	2	10	ns
t_{PLZ}			3	22	3	12	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†		UNIT
			SN74ALS876A		
			MIN	MAX	
f_{max}			30		MHz
t_{PLH}	CLK	Any $\overline{Q}$	4	14	ns
t_{PHL}			4	14	
t_{PHL}	$\overline{PRE}$	Any $\overline{Q}$	6	19	ns
t_{PZH}	$\overline{OE}$	Any $\overline{Q}$	4	18	ns
t_{PZL}			4	18	
t_{PHZ}	$\overline{OE}$	Any $\overline{Q}$	2	10	ns
t_{PLZ}			3	13	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I . . . . . 7 V
Operating free-air temperature range, T_A: SN74AS874, SN74AS876 . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN74AS874			SN74AS876			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
I_{OH}	High-level output current				–15			–15	mA
I_{OL}	Low-level output current				48			48	mA
f_{clock}	Clock frequency		0		125	0		80	MHz
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	2			4.5			ns
		CLK high	3			6.2			
		CLK low	4			6.2			
t_{su}	Setup time before CLK↑	Data	2			4.5			ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	4			5			
t_h	Hold time, data after CLK↑		1			2			ns
T_A	Operating free-air temperature		0		70	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN74AS874 SN74AS876			UNIT
				MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = –2 mA	V_{CC} –2			V
		V_{CC} = 4.5 V,	I_{OH} = –15 mA	2.4	3.3		
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 48 mA		0.35	0.5	V
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			50	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.4 V			–50	µA
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1	mA
I_{IH}		V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
I_{IL}	D	V_{CC} = 5.5 V,	V_I = 0.4 V			–2	mA
	All others					–0.5	
I_O‡		V_{CC} = 5.5 V,	V_O = 2.25 V	–30		–112	mA
I_{CC}	SN74AS874	V_{CC} = 5.5 V	Outputs high		82	133	mA
			Outputs low		92	149	
			Outputs disabled		100	160	
	SN74AS876	V_{CC} = 5.5 V	Outputs high		88	142	
			Outputs low		94	150	
			Outputs disabled		100	160	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†		UNIT
			SN74AS874		
			MIN	MAX	
f_{max}			125		MHz
t_{PLH}	CLK	Any Q	3	8.5	ns
t_{PHL}			4	10.5	
t_{PHL}	$\overline{CLR}$	Any Q	4	9.5	ns
t_{PZH}	$\overline{OE}$	Any Q	2	7	ns
t_{PZL}			3	10.5	
t_{PHZ}	$\overline{OE}$	Any Q	2	6	ns
t_{PLZ}			2	7.5	

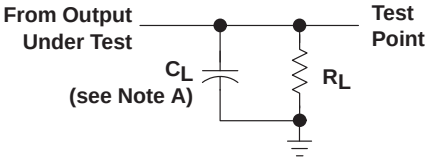
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics (see Figure 1)

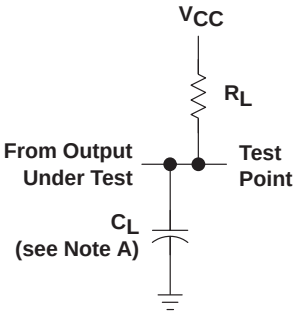
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†		UNIT
			SN74AS876		
			MIN	MAX	
f_{max}			80		MHz
t_{PLH}	CLK	Any $\overline{Q}$	3	8.5	ns
t_{PHL}			4	10.5	
t_{PHL}	$\overline{PRE}$	Any $\overline{Q}$	4	9.5	ns
t_{PZH}	$\overline{OE}$	Any $\overline{Q}$	2	7	ns
t_{PZL}			3	11	
t_{PHZ}	$\overline{OE}$	Any $\overline{Q}$	2	7	ns
t_{PLZ}			2	7	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

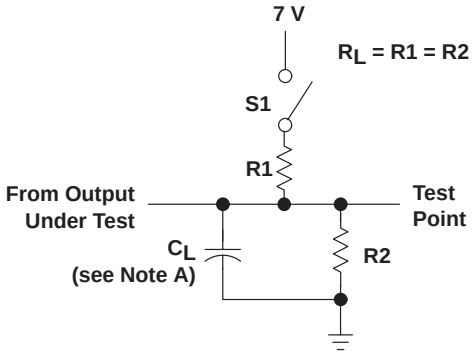
PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



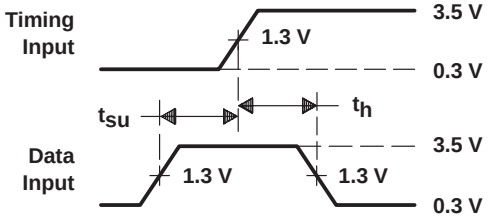
LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS



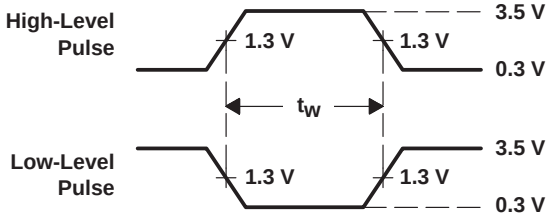
LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



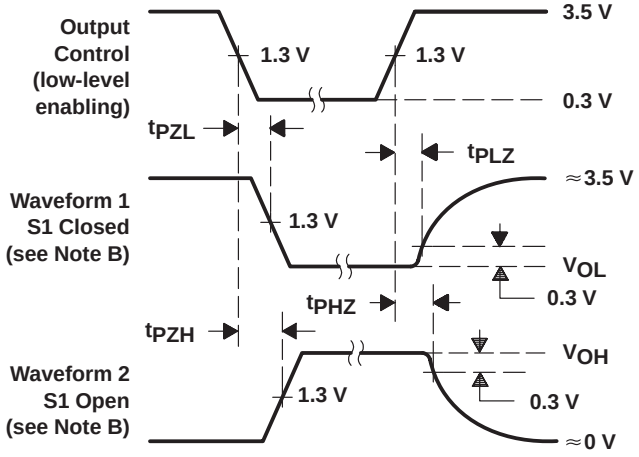
LOAD CIRCUIT
FOR 3-STATE OUTPUTS



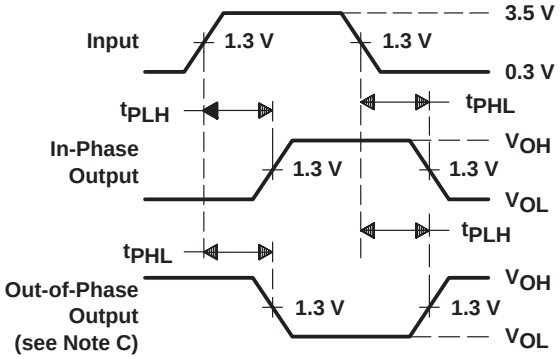
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
84010013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
8401001KA	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI
8401001LA	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN54ALS874BJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS874BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BNSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BNSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BNSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS874BNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS874BNTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS876ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS876ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS876ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS876ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS876ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS876ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS876ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS876ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS874DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS874DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS874DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS874DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
						no Sb/Br)		
SN74AS874DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS874DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS874NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS874NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS876DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS876DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS876DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS876DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS876DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS876DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS876NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS876NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ALS874BFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS874BJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

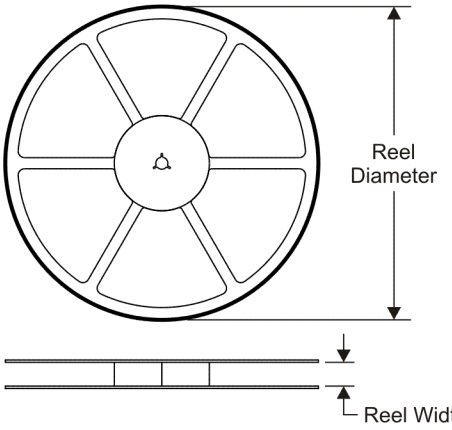
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

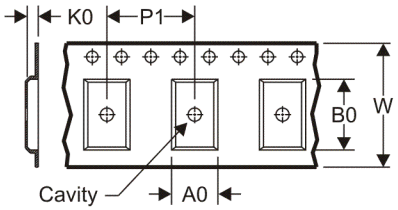
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

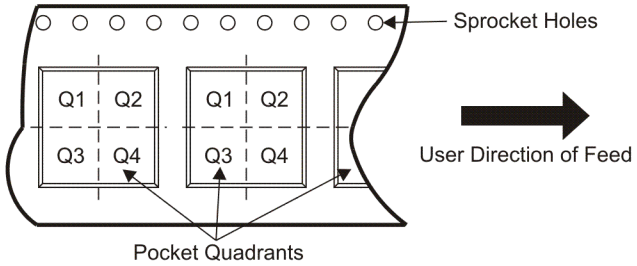


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

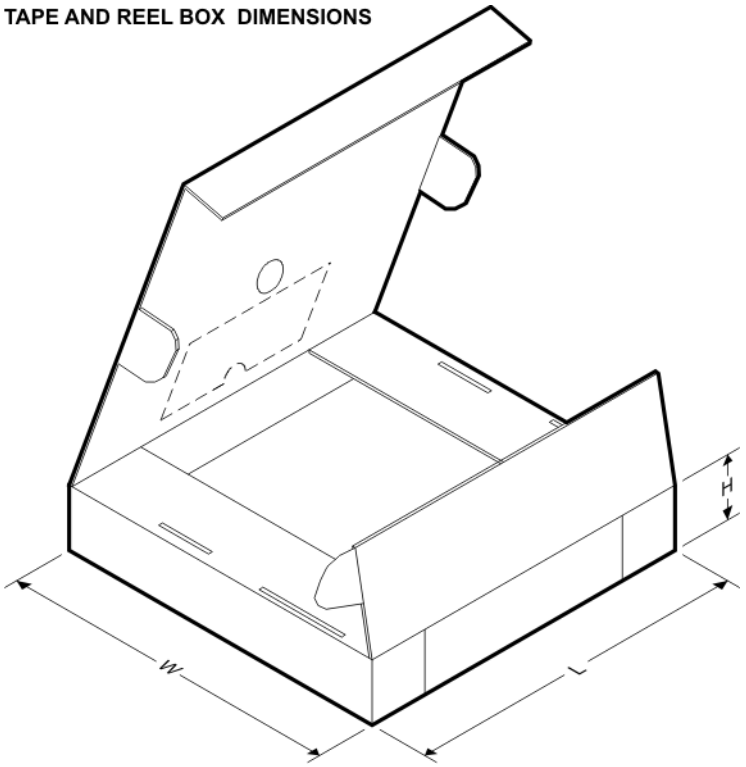
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS874BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ALS874BNSR	SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1
SN74ALS876ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74AS874DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74AS876DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

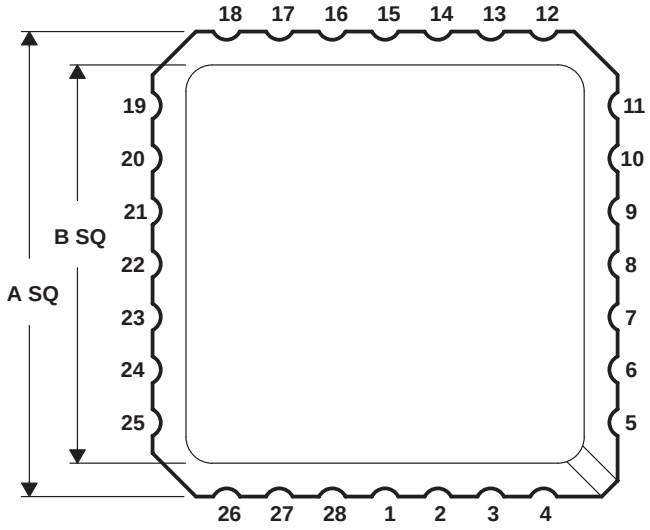


*All dimensions are nominal

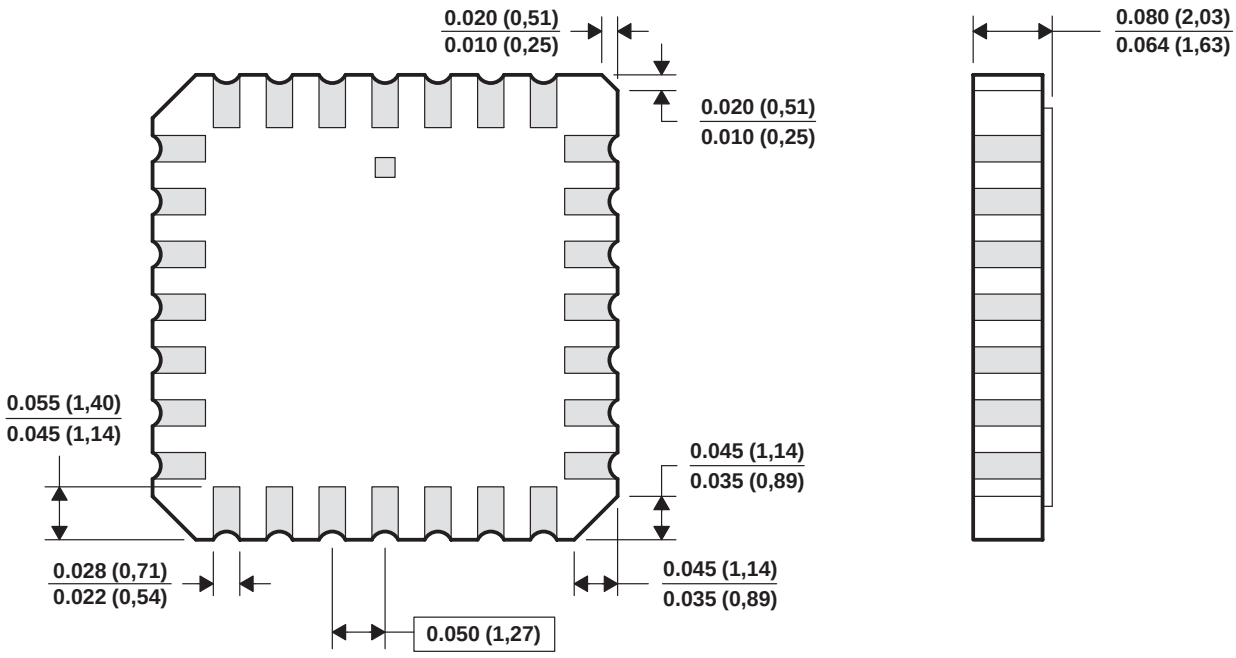
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS874BDWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74ALS874BNSR	SO	NS	24	2000	346.0	346.0	41.0
SN74ALS876ADWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74AS874DWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74AS876DWR	SOIC	DW	24	2000	346.0	346.0	41.0

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



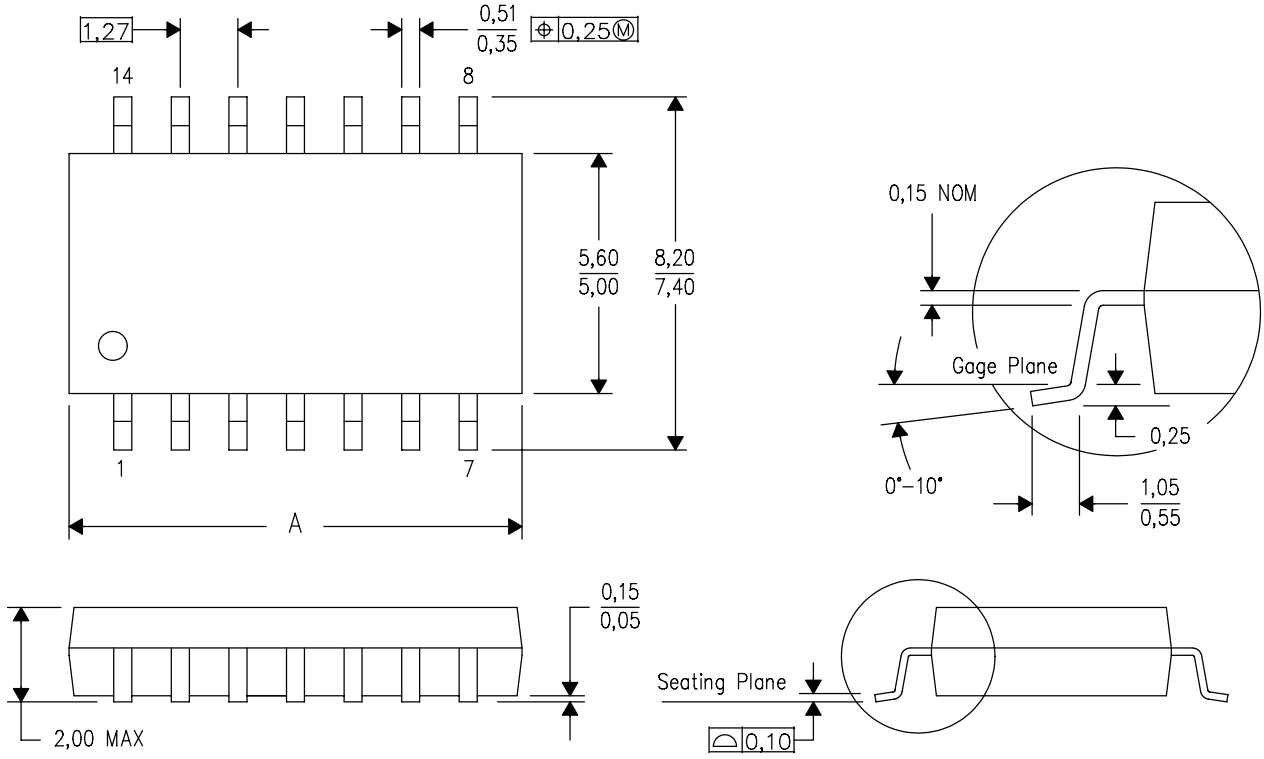
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



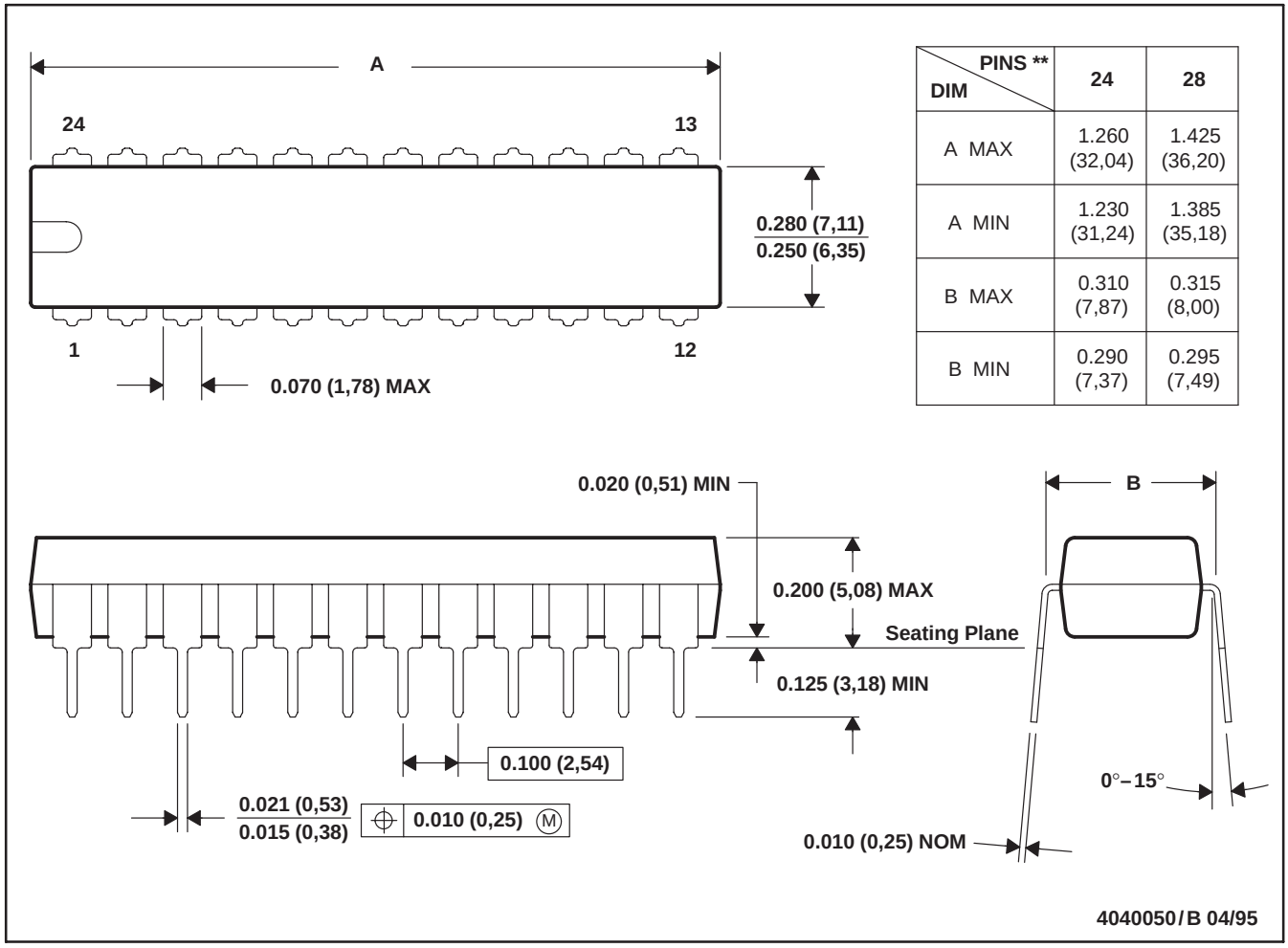
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

NT (R-PDIP-T)** **PLASTIC DUAL-IN-LINE PACKAGE**

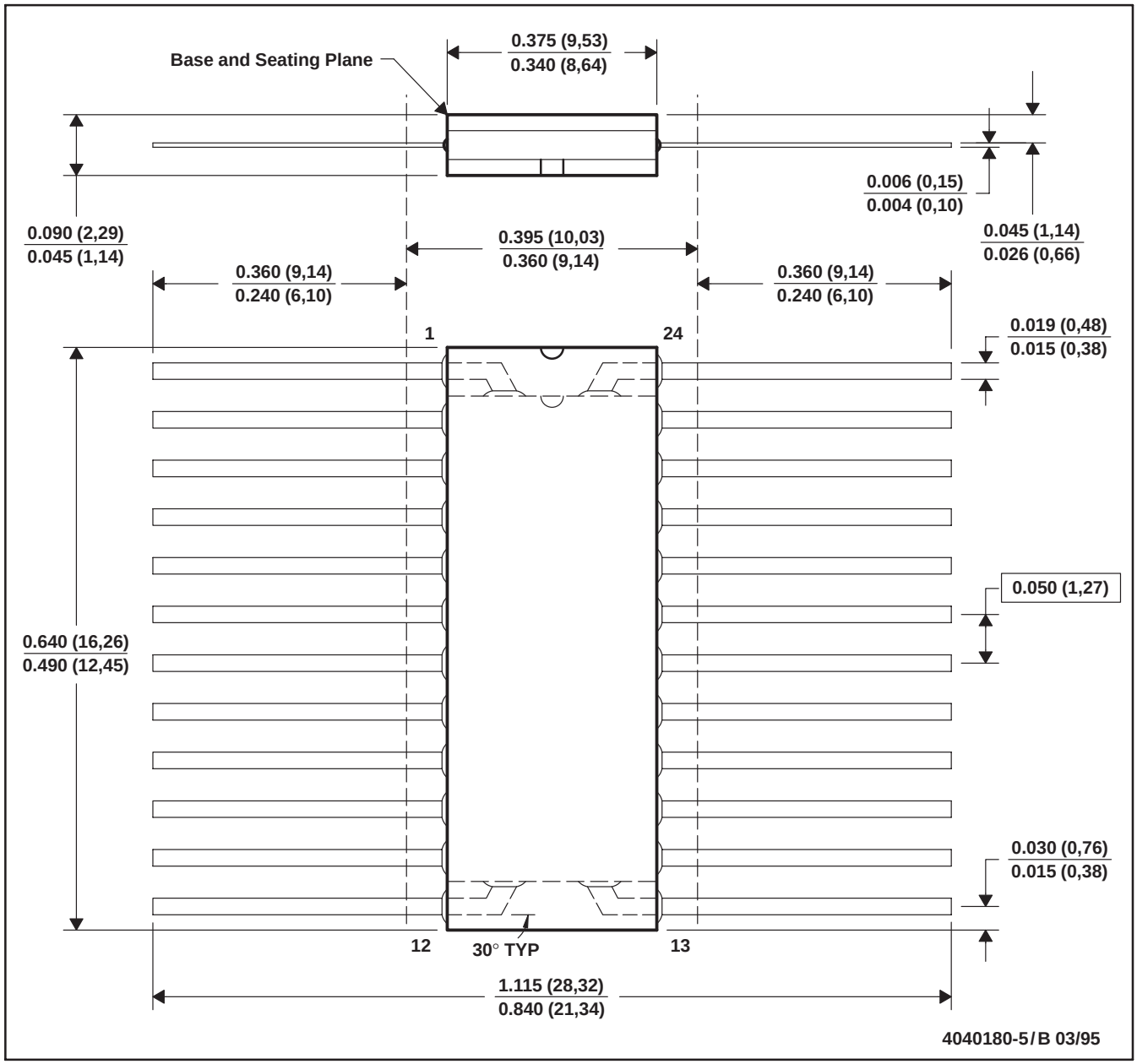
24 PINS SHOWN



DIM \ PINS **	24	28
A MAX	1.260 (32,04)	1.425 (36,20)
A MIN	1.230 (31,24)	1.385 (35,18)
B MAX	0.310 (7,87)	0.315 (8,00)
B MIN	0.290 (7,37)	0.295 (7,49)

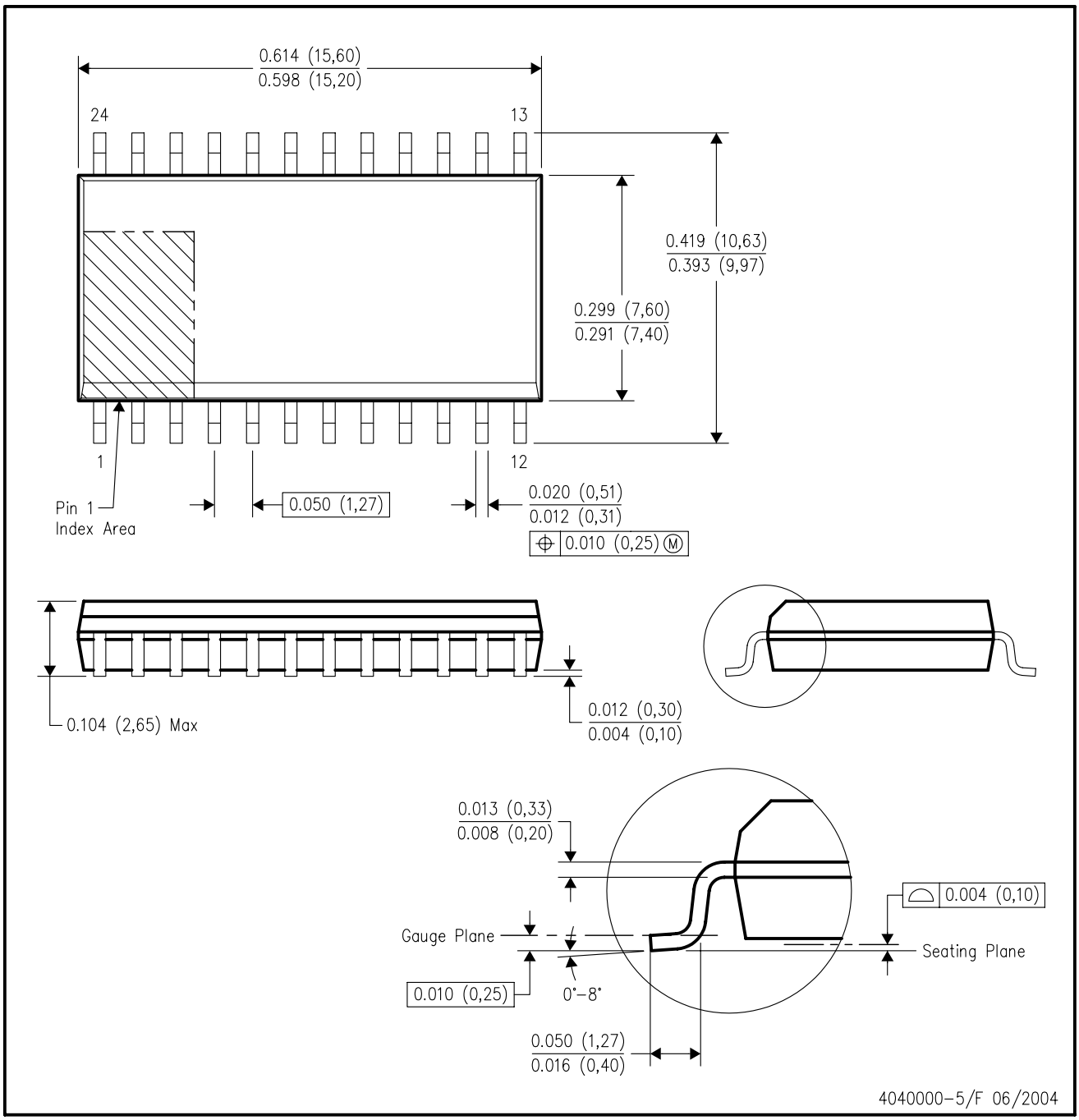
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

W (R-GDFP-F24) **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
E. Index point is provided on cap for terminal identification only.

DW (R–PDSO–G24) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

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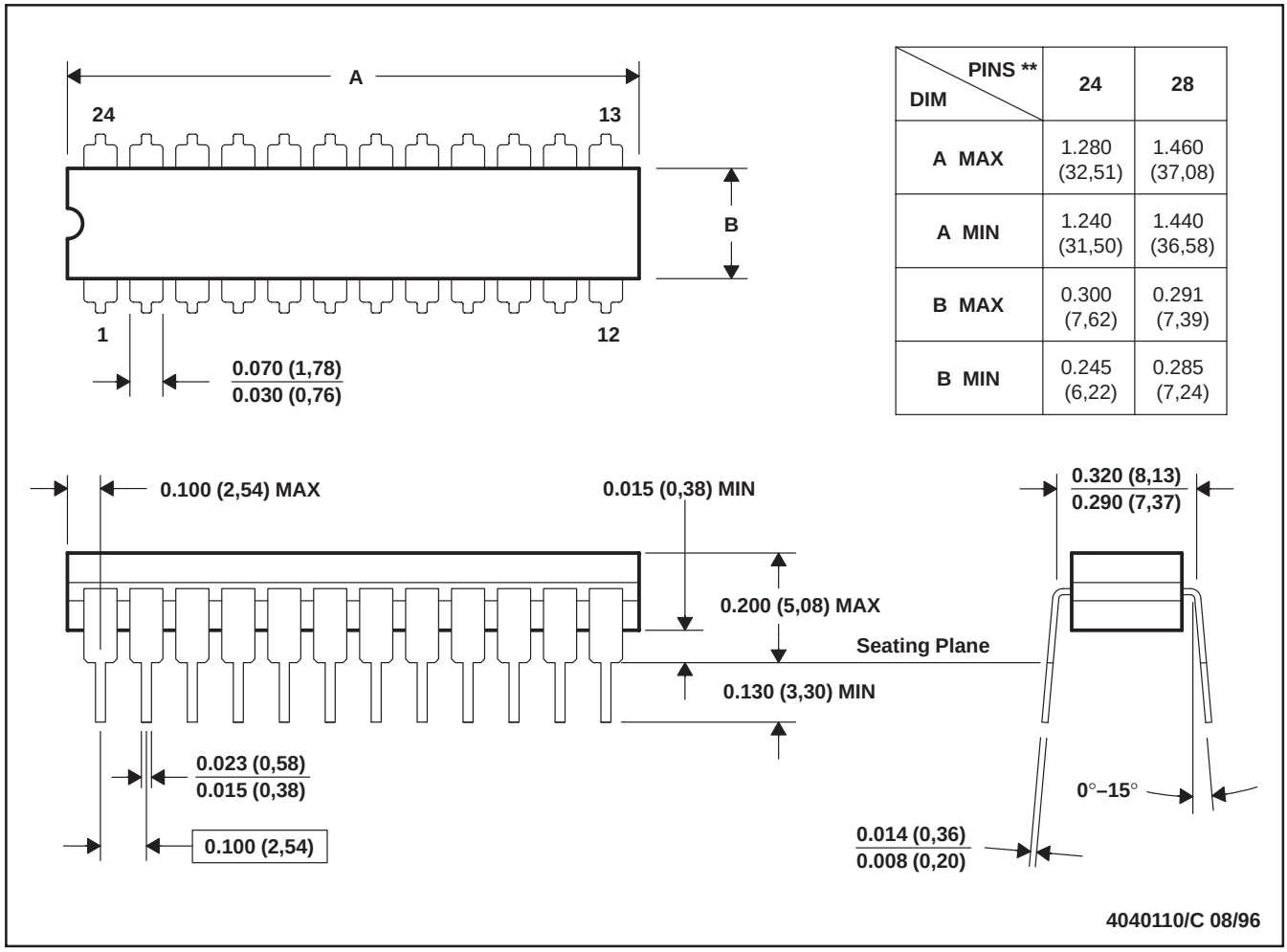
JT (R-GDIP-T)** **CERAMIC DUAL-IN-LINE**

24 LEADS SHOWN



DIM \ PINS **	24	28
A MAX	1.280 (32,51)	1.460 (37,08)
A MIN	1.240 (31,50)	1.440 (36,58)
B MAX	0.300 (7,62)	0.291 (7,39)
B MIN	0.245 (6,22)	0.285 (7,24)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification.
E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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